The LT1619 is a fixed frequency PWM controller for implementing current mode DC/DC converters with minimum external parts. The LT1619 operates with input voltages ranging from 1.9V to 18V and is suitable for a variety of battery-powered and distributed DC/DC converters. The internal rail-to-rail N-channel MOSFET driver operates either from the input in the nonbootstrapped mode or from the output in bootstrapped operation. The driver is designed to drive a low side power transistor in boost, SEPIC, flyback and other topologies.

Converter efficiency is improved at heavy loads with a 53mV current sense voltage and at light load with Burst Mode operation. The operating frequency is internally set at 300kHz. The oscillator can also be synchronized externally up to 500kHz. No load quiescent current is 140μA and shutdown current is 15μA.

The LT1619 is available in 8-lead MSOP and SO packages.

**FEATURES**
- Wide VIN Range: 1.9V to 18V
- 300kHz Fixed Frequency Current Mode Control
- 1A Rail-to-Rail N-Channel MOSFET Driver
- Low 53mV Current Limit Threshold Voltage Improves Efficiency
- Implements Boost, SEPIC and Flyback Converters Requiring Low Side Power Transistors
- Internal Current Sense Amplifier with Leading Edge Blanking
- Up to 500kHz External Synchronization
- Burst Mode® Operation for High Efficiency at Light Load
- 140μA Quiescent Current
- 15μA Shutdown Current
- 8-Lead MSOP and SO Packages

**APPLICATIONS**
- 3.3V to 5V DC/DC Converters
- Distributed Power Supplies
- Isolated Power Supplies

**DESCRIPTION**

**TYPICAL APPLICATION**

![Typical Application Diagram](image-url)

**Figure 1. High Efficiency 3.3V to 5V DC/DC Converter**
**LT1619**

**ABSOLUTE MAXIMUM RATINGS** *(Note 1)*

- Input Voltage \( (V_{IN}) \) ......................... –0.3V to 20V
- Gate Drive Supply Voltage \( (DRV) \) .......... –0.3V to 20V
- Shutdown/Synch Voltage \( (S/S) \) ................ –0.3V to 20V
- Feedback Voltage \( (FB) \) .............................................. \( V_{IN} \)
- Compensation Voltage \( (V_C) \) ............................. 3V
- Gate Drive Output Current \( (GATE) \) ................. ±1.5A
- Current Sense Voltage \( (SENSE) \) ................. –0.5V to \( V_{IN} \)
- Operating Temperature Range (Note 2) .. –40°C to 85°C
- Junction Temperature (Note 3)............................. 125°C
- Storage Temperature Range ................ –65°C to 150°C
- Lead Temperature (Soldering, 10 sec).............. 300°C

**PACKAGE/ORDER INFORMATION**

<table>
<thead>
<tr>
<th>ORDER PART NUMBER</th>
<th>TOP VIEW</th>
</tr>
</thead>
<tbody>
<tr>
<td>LT1619EMS8</td>
<td>![TOP VIEW](MS8 PACKAGE 8-LEAD PLASTIC MSOP T_{JMAX} = 125°C, ( \theta_{JA} = 200°C/W ))</td>
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<td>MS8 PART MARKING</td>
<td>LTHC</td>
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<tr>
<td>ORDER PART NUMBER</td>
<td>TOP VIEW</td>
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<tr>
<td>LT1619ES8</td>
<td>![TOP VIEW](S8 PACKAGE 8-LEAD PLASTIC SO T_{JMAX} = 125°C, ( \theta_{JA} = 120°C/W ))</td>
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<tr>
<td>S8 PART MARKING</td>
<td>1619</td>
</tr>
</tbody>
</table>

Consult LTC Marketing for parts specified with wider operating temperature ranges.

**ELECTRICAL CHARACTERISTICS**

The ● denotes specifications which apply over the full operating temperature range, otherwise specifications are at \( T_A = 25°C \).

\( V_{IN} = V_{DRV} = 2.5V, V_{S/S} = V_{IN}, \) COMP open, \( V_{SENSE} = 0V \) unless otherwise noted.

<table>
<thead>
<tr>
<th>PARAMETER</th>
<th>CONDITIONS</th>
<th>MIN</th>
<th>TYP</th>
<th>MAX</th>
<th>UNITS</th>
</tr>
</thead>
<tbody>
<tr>
<td>Reference Voltage</td>
<td>Measured at the FB Pin</td>
<td>●</td>
<td>1.22</td>
<td>1.24</td>
<td>1.26</td>
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<tr>
<td>Reference Line Regulation</td>
<td>( 1.9V \leq V_{IN} \leq 18V )</td>
<td>●</td>
<td>0.004</td>
<td>0.05</td>
<td>%/V</td>
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<tr>
<td>FB Input Bias Current</td>
<td>( V_{FB} = V_{REF} )</td>
<td></td>
<td>10</td>
<td>25</td>
<td>nA</td>
</tr>
<tr>
<td>Error Amplifier Transconductance</td>
<td></td>
<td>80</td>
<td>170</td>
<td>260</td>
<td>( \mu\Omega^{-1} )</td>
</tr>
<tr>
<td>Error Amplifier Output Source Current</td>
<td>( V_{FB} = 1V, V_{COMP} = 1V )</td>
<td>4</td>
<td>8.7</td>
<td>14</td>
<td>( \mu\text{A} )</td>
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<tr>
<td>Error Amplifier Output Sink Current</td>
<td>( V_{FB} = 1.5V, V_{COMP} = 1V )</td>
<td>4</td>
<td>8.7</td>
<td>14</td>
<td>( \mu\text{A} )</td>
</tr>
<tr>
<td>Error Amplifier Clamp Voltage</td>
<td>( V_{FB} = 1V )</td>
<td>1.6</td>
<td>2.2</td>
<td>2.2</td>
<td>V</td>
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<tr>
<td>Undervoltage Lockout Threshold</td>
<td></td>
<td>1.65</td>
<td>1.85</td>
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<td>V</td>
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<tr>
<td>Input Voltage Range</td>
<td></td>
<td>●</td>
<td>1.9</td>
<td>18</td>
<td>V</td>
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<tr>
<td>Switching Frequency</td>
<td>( 1.9V \leq V_{IN} \leq 18V )</td>
<td>●</td>
<td>220</td>
<td>300</td>
<td>360</td>
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<tr>
<td>Synchronization Frequency Range</td>
<td></td>
<td>370</td>
<td>500</td>
<td></td>
<td>kHz</td>
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<tr>
<td>Maximum Duty Cycle</td>
<td></td>
<td>●</td>
<td>88</td>
<td>92</td>
<td>%</td>
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<tr>
<td>Current Limit Threshold</td>
<td></td>
<td>●</td>
<td>40</td>
<td>53</td>
<td>66</td>
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<tr>
<td>Burst Mode Operation Current Limit</td>
<td></td>
<td></td>
<td>10</td>
<td></td>
<td>mV</td>
</tr>
</tbody>
</table>
### ELECTRICAL CHARACTERISTICS

The ● denotes specifications which apply over the full operating temperature range, otherwise specifications are at $T_A = 25°C$. $V_{IN} = V_{DRV} = 2.5V$, $V_{S/S} = V_{IN}$, COMP open, $V_{SENSE} = 0V$ unless otherwise noted.

<table>
<thead>
<tr>
<th>PARAMETER</th>
<th>CONDITIONS</th>
<th>MIN</th>
<th>TYP</th>
<th>MAX</th>
<th>UNITS</th>
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<tbody>
<tr>
<td>Current Sense Input Current</td>
<td>$V_{SENSE} = 0V$</td>
<td>●</td>
<td>$-90$</td>
<td>$-120$</td>
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<td>Current Limit Delay</td>
<td></td>
<td></td>
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<td></td>
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<tr>
<td>Driver Output Rise Time</td>
<td>$C_L = 3300pF$</td>
<td></td>
<td>30</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Driver Output Fall Time</td>
<td>$C_L = 3300pF$</td>
<td></td>
<td>35</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Driver Output High Level</td>
<td>$I_{OUT} = -20mA$</td>
<td></td>
<td>$V_{DRV} - 0.6$</td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td>$I_{OUT} = -200mA$</td>
<td></td>
<td>$V_{DRV} - 0.35$</td>
<td></td>
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<tr>
<td>Driver Output Low Level</td>
<td>$I_{OUT} = 20mA$</td>
<td></td>
<td>100</td>
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<tr>
<td></td>
<td>$I_{OUT} = 200mA$</td>
<td></td>
<td>0.5</td>
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<tr>
<td>Shutdown Driver Output Level</td>
<td>$V_{S/S} = 0V$, $I_{OUT} = 20mA$</td>
<td></td>
<td>100</td>
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<td></td>
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<td>Idle Mode Driver Output Level</td>
<td>$V_{S/S} = V_{IN}$, $V_{FB} = 1.5V$, $I_{OUT} = 20mA$</td>
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<td>100</td>
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<td>S/S Pin Current</td>
<td>$V_{S/S} = V_{IN}$</td>
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<td></td>
<td>$V_{S/S} = 0V$</td>
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<td>$-2$</td>
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<td>Operating Supply Current</td>
<td>$V_{FB} = 1V$</td>
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<tr>
<td>Quiescent Supply Current</td>
<td>$V_{S/S} = V_{IN}$, $V_{FB} = 1.5V$</td>
<td></td>
<td>●</td>
<td>140</td>
<td>220</td>
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<tr>
<td>Shutdown Supply Current</td>
<td>$V_{S/S} = 0V$</td>
<td></td>
<td>15</td>
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<td>19</td>
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<td></td>
<td>$V_{S/S} = 0V$, $V_{IN} = 18V$, $T_A = 85°C$</td>
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<tr>
<td>Shutdown Threshold</td>
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<td></td>
<td>0.45</td>
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</tr>
<tr>
<td>Shutdown Delay</td>
<td></td>
<td></td>
<td>12</td>
<td></td>
<td>17</td>
</tr>
</tbody>
</table>

**Note 1:** Absolute Maximum Ratings are those values beyond which the life of the device may be impaired.

**Note 2:** The LT1619E is guaranteed to meet performance specifications from 0°C to 70°C. Specifications over the −40°C to 85°C operating temperature range are assured by design, characterization and correlation with statistical process controls.

**Note 3:** $T_J$ is calculated from the ambient temperature $T_A$, the power dissipation $P_D$ and the thermal resistance $\theta_{JA}$ of the package according to the formula:

$$T_J = T_A + P_D \times \theta_{JA}$$

### TYPICAL PERFORMANCE CHARACTERISTICS

![Bandgap Voltage vs Temperature](image1)

![$I_{S/S}$ vs $V_{S/S}$](image2)

![S/S Pin Current vs Temperature](image3)
TYPICAL PERFORMANCE CHARACTERISTICS

- **Shutdown Supply Current vs Input Voltage**
- **Idle Mode Supply Current vs Temperature**
- **Frequency Deviation from Nominal vs Temperature**

- **Maximum Duty Ratio vs Temperature**
- **Deviation from Nominal Frequency vs Input Voltage**
- **Current Limit Threshold vs Temperature**

- **Burst Mode Operation Current Limit Threshold vs Temperature**
- **SENSE Pin Input Bias Current vs Temperature**
- **SENSE Pin Input Bias Current vs Sense Voltage**
PIN FUNCTIONS

S/S (Pin 1): Shutdown and Synchronization. Shutdown is active low with a typical threshold voltage of 0.9V. For normal operation, the S/S pin is tied to VIN. To externally synchronize the controller, drive the S/S pin with pulses.

FB (Pin 2): The inverting Input of the Error Amplifier. Connect the resistor divider tap here. Set VOUT according to VOUT = 1.24(1 + R1/R2). See Figure 1.

Vc (Pin 3): Compensation Pin for the Error Amplifier. Vc is the output of the transconductance amplifier. Overall loop is compensated with an RC network from this pin to the ground.

GND (Pin 4): Ground. Connect to local ground plane.

SENSE (Pin 5): The Input of the Current Sense Amplifier. The SENSE pin is connected to the source of the N-channel MOSFET and to a sense resistor to the ground. The current limit threshold is internally set at 53mV, giving a maximum switch current of 53mV/RSENSE.

GATE (Pin 6): The Output of the MOSFET Driver.

DRV (Pin 7): The Pull-Up Supply of the MOSFET Driver. Tie this pin to VIN (Pin 8) for nonbootstrapped operation or to the converter output for bootstrapped operation.

VIN (Pin 8): Supply or Battery Input. Must be closely bypassed to the ground plane.

BLOCK DIAGRAM

Figure 2. LT1619 Block Diagram
The LT1619 is a fixed frequency current mode switching regulator PWM controller that can be used in boost, SEPIC or flyback modes. The device operates from an input supply range of 1.9V to 18V, and has a separate supply pin (DRV) for the gate driver. The DRV pin can be bootstrapped to VOUT for additional gate enhancement in low voltage applications like 3.3V to 5V boost converters, or connected to the input supply for higher voltage inputs.

To best understand operation of the LT1619, please refer to Figure 2, the Block Diagram. The gate drive circuit turns on the external MOSFET at the trailing edge of oscillator output signal CLK. MOSFET current is sensed with an external resistor (RSENSE of Figure 1). A leading edge blanking circuit disables the current sense amplifier for 280ns immediately following switch turn-on, preventing gate charging current from prematurely tripping the PWM comparator. A slope compensating ramp, derived from the oscillator, is added to the current sense output. The driver turns off the MOSFET when this sum exceeds the error amplifier output VC. The switch current is limited with a separate comparator. The compensating ramp is a progressive nonlinear function of the operating duty ratio whereas the current limit does not vary with the duty ratio.

Error amplifier output VC determines the peak switch current required to regulate the output voltage. VC can be considered a measure of output current. At heavy loads, VC is in its upper range. Average and peak inductor currents are high. In this range, the inductor tends to run in continuous conduction mode (CCM), where current is always flowing in the inductor. As load current decreases, average and peak inductor current decreases. When the average inductor current falls below 1/2 of the peak-to-peak inductor current ripple, the converter enters discontinuous conduction mode (DCM), where current in the inductor reaches zero sometime during the discharge phase.

Further reduction in output current moves VC towards its lower operating range, decreasing inductor current. Hysteretic comparator A1 determines if VC is too low for the LT1619 to operate efficiently. As VC falls below the trip voltage VB, A1’s output goes high, turning off all blocks except the error amplifier, A1 and A2. The LT1619 enters the idle state and switching stops. The device draws just 140μA from the input in the idle state. Output load current discharges the output capacitor, causing the output voltage to decrease. As VOUT decreases, VC increases. As VC increases above VB, switching action begins, delivering power to the output. The switch current sense threshold is about 10mV in this VC region. If the output load remains light, the output voltage will rise and VC will fall, causing the converter to idle again. This is known as Burst Mode operation. The burst frequency depends on input voltage, output voltage, inductance and output capacitance. Output voltage ripple during Burst Mode operation is usually higher than when the converter is switching continuously. Burst Mode operation increases light load efficiency because it delivers more energy per clock cycle than possible with discontinuous mode operation and extremely low peak switch current, allowing fewer switching cycles to maintain a given output. IC supply current therefore becomes a small fraction of the total input current.

**Setting Output Voltage**

The output voltage of the LT1619 is set with resistive divider R1 and R2 connected from the output to ground as detailed in Figure 3. The divider tap is tied to the device FB pin. Current through R2 should be significantly higher than the FB pin bias current of 25nA. With R2 = 10k, the input bias current of the error amplifier is 0.02% of the current in R2.

\[
V_O = 1.24 \left( 1 + \frac{R_1}{R_2} \right)
\]

**Figure 3. Feedback Resistive Divider**

**Synchronization and Shutdown**

The S/S pin (Pin 1) can be used to synchronize the oscillator to an external source. The S/S pin is tied to the input (VIN > 1.9V) for normal operation. The oscillator in the LT1619 can be externally synchronized by driving the S/S pin with a pulse train with an amplitude of at least 1V. The maximum allowable rise time is a function of the pulse amplitude, as shown in Table 1. Rise times equal to
or less than the number specified in Table 1 are acceptable. The maximum duty cycle is essentially unaffected by synchronization.

The device will go into shutdown mode if the S/S pin voltage stays below the shutdown threshold of 0.45V for more than 33μs. This shutdown delay is reset whenever the S/S pin voltage rises above the shutdown threshold. Applying a logic low signal at the S/S pin causes the gate drive output to go low. Although all circuits in the LT1619 are disabled, the pull-down circuit in the MOSFET buffer is still biased on. It is capable of shunting any leakage or transient current at the GATE pin to ground, eliminating the need for an external bleed resistor. The LT1619 consumes 15μA in shutdown.

The LT1619 is guaranteed to start with a minimum \( V_{\text{IN}} \) of 1.85V. Comparator A2 senses the input voltage and generates an undervoltage lockout (UVLO) signal if \( V_{\text{IN}} \) falls below this minimum. While in undervoltage lockout, \( V_C \) is pulled low and the LT1619 stops switching. The supply current drawn by the device falls to 140μA.

### Applications Information

#### Inductor

The value of the inductor is usually selected so that the peak-to-peak ripple current is less than 30% of the maximum inductor current. The inductor should be able to handle the maximum inductor current at full load without saturation. Powder iron cores are not suitable for high frequency switch mode power supply applications because of their high core losses. Ferrite cores have very low core losses and are the material of choice for high frequency DC/DC converters.

#### Power MOSFET Driver

The LT1619 is capable of driving a low side N-channel power MOSFET with up to 60nC of total gate charge (\( Q_g \)). An external driver is recommended for MOSFETs with greater than 80nC of total gate charge. The peak gate drive current varies from 0.5A with \( V_{\text{DRV}} = 2.5V \) to 1.2A with \( V_{\text{DRV}} = 10V \). The MOSFET driver is capable of charging the gate of the power MOSFET to within 350mV of the upper gate drive supply rail (DRV). It can also pull the gate of the MOSFET to within 100mV of ground during turnoff. The upper supply rail of the gate drive is brought out as a device pin (DRV) for design flexibility. In a boost converter design, the DRV pin can be tied to the converter output if the minimum input voltage is insufficient to fully enhance the power MOSFET. During start-up, the MOSFET is driven with a gate voltage starting from \( V_{\text{IN}} - V_D \) (\( V_D \) is the forward voltage of the rectifying diode). As the output voltage rises, the gate drive also increases until steady state is reached. If the steady-state converter output voltage exceeds the maximum allowable gate source voltage and the input voltage is sufficient to enhance the MOSFET, the DRV pin is tied to the input supply. For a SEPIC converter, the DRV pin can be tied to the input or diode OR’ed from the input and the output (Figure 4).

#### Table 1. Maximum Allowable Rise Time of Synchronization Pulse. Rise Time Can Be Slower if Clock Amplitude is Higher

<table>
<thead>
<tr>
<th>SYNCHRONIZATION AMPLITUDE (V)</th>
<th>MAXIMUM ALLOWABLE RISE TIME (ns)</th>
</tr>
</thead>
<tbody>
<tr>
<td>1.2</td>
<td>120</td>
</tr>
<tr>
<td>1.5</td>
<td>220</td>
</tr>
<tr>
<td>2.0</td>
<td>350</td>
</tr>
<tr>
<td>2.5</td>
<td>470</td>
</tr>
<tr>
<td>3.0</td>
<td>530</td>
</tr>
</tbody>
</table>

#### Figure 4. SEPIC Converter with Diode OR’ed Gate Drive Supply
Power MOSFET

MOSFET power dissipation can be separated into frequency independent and frequency dependent components. The $R_{DS(ON)}$ loss in the switch is the product of the mean square switch current and switch $R_{DS(ON)}$ and it does not vary with the operating frequency.

The frequency-dependent switching losses consist of 1) switch transition loss due to finite rise and fall times of the drain source voltage and the drain current 2) gate switching loss, i.e., a packet of charge $Q_g$ (the total gate charge) which is moved from the gate drive power supply to ground in every switch cycle, and 3) the drain switching loss, charge stored on the parasitic drain capacitance, $C_{DSS}$ is dumped to ground as the switch is turned on. The transistor loss can be expressed as:

$$P_{LOSS} = I_{DRMS}^2 R_{DS(ON)} + \text{transition loss} + Q_g V_G f_S + \frac{1}{2} C_{DSS} V_{DS(OFF)}^2 f_S$$

where the transition loss can be estimated with:

$$\text{Transition Loss} = I_D \frac{C_{RSS} V_{DS(OFF)}^2 f_S}{I_{G(AVG)}}$$

$Q_g$ = The total gate charge
$V_G$ = Gate drive voltage = $V_{DRV}$
$I_{G(AVG)}$ = The average MOSFET buffer output current
$f_S$ = Operating frequency
$C_{RSS}$ = The average $C_{GD}$ between $V_{DS} = 0V$ and $V_{DS} = V_{DS(OFF)}$

At low $V_{DS(OFF)}$ ($\leq 12V$) and operating frequencies below 500kHz, the ohmic losses often dominate. For high voltage converters, the transition loss and $C_{DSS}$ charge dumping loss can dramatically impact the converter efficiency. MOSFETs with lower parasitic capacitances but higher $R_{DS(ON)}$ may actually provide better efficiency in these situations.

Capacitors

In a switch mode DC/DC converter, output ripple voltage is the product of the equivalent series resistance (ESR) of the output capacitor and the peak-to-peak capacitor current. Depending on topology, current feeding the output capacitor can be continuous or discontinuous. The input current can also be continuous or discontinuous even if the inductor current itself is continuous. In boost topology, the inductor is in series with the input source so the input current is continuous and the output current is discontinuous. In buck-boost or flyback converters, the inductor is not in series with the input source nor the output, so neither the input current nor output current is continuous.

Whenever a terminal current is discontinuous, the capacitor at that terminal should be chosen to handle the ripple current. Capacitor reliability will be adversely affected if the ripple current exceeds the maximum allowable ratings. This maximum rating is specified as the RMS ripple current. Several capacitors may be mounted in parallel to meet the size and ripple current requirements.

Besides the ripple voltage requirements, the output capacitor also needs to be sized for acceptable output voltage variation under load transients.

Current Sensing Resistor $R_{SENSE}$

The LT1619 drives a low side N-channel MOSFET switch. The switch current is sensed with an external resistor $R_{SENSE}$ connected between the source of the MOSFET and ground. The internal blanking circuit blocks the voltage spike developed across $R_{SENSE}$ for 280ns at switch turn-on. The switch is turned off when the instantaneous voltage across $R_{SENSE}$ exceeds the current limit threshold, $V_{SENSE}$. Allowing variations in $V_{SENSE}$ yields:

$$R_{SENSE} = \frac{V_{SENSE(MIN)}}{I_L(MAX)}$$

The current limit threshold is constant and does not vary with duty ratio.

Due to low signal level of the sense voltage, low inductance sense resistors are required to reduce switching noise. Low TC resistors maintain constant current limit over temperature. Dale WSL and IRC series sense resistors meet these criteria.
**Applications Information**

**Diode**

Schottky diodes are recommended for low output voltage applications because of their low forward voltage. Since Schottky diodes have negligible stored charge, charge dumping loss is also reduced. The reverse breakdown voltage of the diode should exceed the maximum reverse voltage stress of the topology used. The diode should also be able to carry the peak diode current with acceptable forward voltage. For the boost converter in Figure 1, the peak inductor current is approximately 5A. A Motorola MBRD835 is used due to its low forward voltage.

**Lowering Burst Mode Operation Current Limit**

The LT1619 automatically enters Burst Mode operation as $V_C$ voltage falls below $V_B$. The corresponding switch current is the Burst Mode operation switch current threshold, $I_{D(BURST)}$.

The effective Burst Mode operation current threshold can be lowered by adding an offset to the input of the current sense amplifier so that the switch current appears higher to the PWM comparator. This has the effect of shifting the $V_C$ operating range above $V_B$. Although Burst Mode operation is not entirely disabled, the peak switch current before entering Burst Mode operation is greatly reduced due to the offset of the current sense amplifier. The peak switch current is also determined by the current sense amplifier blanking.

To lower the Burst Mode operation current sense threshold, a resistor $R_{OS}$ is added between the SENSE pin and the sense resistor $R_{SENSE}$ (Figure 5). The input bias current $I_{BIAS}$ of the current sense amplifier, which has a tolerance of ±25% and is temperature stable, develops an offset voltage at the sense input. The value of $R_{OS}$ required for non-Burst Mode operation can be obtained with the expression:

$$I_{BIAS}R_{OS} \geq V_{SENSE(BURST)}$$

where

$$V_{SENSE(BURST)} = (\text{Burst Mode operation peak switch current, } I_{D(BURST)}) \cdot R_{SENSE}$$

For example, if $I_{BIAS} = 120\mu A$ and $V_{SENSE(BURST)} = 10mV$:

$$R_{OS} \geq \frac{10mV}{120\mu A} = 83\Omega$$

Allowing for 25% and 30% variations in $I_{BIAS}$ and $V_{SENSE(BURST)}$ respectively:

$$R_{OS} = (1.25)(1.3)(83\Omega)$$

Choose $R_{OS} = 137\Omega$ to completely disable Burst Mode operation. Lower values of $R_{OS}$ (for example, 50Ω to 100Ω) can be used to lower the effective Burst Mode current limit.

The value of the sense resistor is then adjusted to compensate for the reduced full-scale sense voltage.

$$I_{BIAS}R_{OS} + I_{L(MAX)}R_{SENSE} = 40mV$$

**Filtering Current Sense Signal**

In a current mode converter, the current sense circuit senses the switch current and terminates the switch conduction. In the LT1619, the current sense amplifier has a full-scale input voltage range from the ground to the current limit threshold (53mV). Due to high speed switching transients and parasitic trace inductances, the current sense signal $V_{SENSE}$ tends to be noisy. If the $V_{SENSE}$ switching transient is excessive, the current sense amplifier will amplify the spurious transient instead, resulting in jittery operation. In situations where the internal leading edge blanking is inadequate, a lowpass filter (Figure 6) with corner frequency about 5 times the switching frequency can be used to further attenuate high speed switching transients. In Figure 6 the lowpass filter $R_{OS}$ and $C_S$ has a corner frequency of:
**APPLICATIONS INFORMATION**

\[ f_{\text{CORNER}} = \frac{1}{2\pi R_{\text{OS}} C_S} \approx 5f_S \]

(The input impedance of the sense amplifier at the SENSE pin is 2500Ω and \( R_{\text{OS}} \) is typically less than 137Ω.) Typical values for \( R_{\text{OS}} \) and \( C_S \) are 100Ω and 1nF. The 100Ω value for \( R_{\text{OS}} \) reduces Burst Mode threshold; use 10Ω and 10nF when this is not desireable.

**Use of Shutdown Function to Modify Undervoltage Lockout**

The LT1619 is designed to operate from an input supply with voltage as low as 1.85V. Shutdown is activated when the S/S pin is pulled below 0.45V. The shutdown threshold is slightly greater than one junction diode forward voltage and has the temperature characteristics of a junction diode. The S/S pin is normally tied to the input when operating from a low voltage input source.

Consider the 12V to –65V isolated flyback converter (see Typical Applications). The converter draws 3A at low line while delivering 0.4A to the output. If the S/S pin is tied to the input, then the LT1619 will start switching as soon as \( V_{\text{IN}} \) exceeds the internal UVLO threshold. With full load, the converter can draw much higher than the steady-state 3A from the input source during start-up. If the input source is current limited, the input voltage will collapse and latch low.

The start-up problem can be prevented by adding a zener diode and a resistor to the S/S pin (Figure 7). This is equivalent to increasing undervoltage lockout voltage of the controller. Before \( V_{\text{IN}} \) exceeds the zener voltage \( V_Z \), the S/S pin current is shunted to the ground through the resistor R3. The voltage developed across R3 due to \( I_{\text{S/S}} \) should be less than the shutdown threshold. The LT1619 remains off until \( V_{\text{IN}} \) exceeds the sum of \( V_Z \) and the shutdown threshold. True zener diodes (\( BV < 5V \)) and higher voltage avalanche diodes have different I-V characteristics (Figure 8). They need to be biased appropriately (value of R3) in order to obtain correct UVLO threshold.

When implementing UVLO with converters with high input ripple voltages (such as flyback and forward), the circuit in Figure 7 is modified and shown in Figure 9.
Here the input voltage ripple is filtered with R3, R4 and C1 so as to prevent the input ripple from falsely tripping the LT1619 synchronization circuit. It is recommended that:

\[ R_4 \approx \frac{1}{5} R_3 \]

and

\[ \frac{1}{2\pi (R_3 || R_4) C_1} \ll f_{\text{OSC}} \]

Implementation of Hysteretic UVLO with External Synchronization

The UVLO circuit shown in Figure 10 operates down to 0.9V supply voltage. Algebraically the UVLO trip points are:

\[ V_{\text{INH}} = V_Z + V_{\text{BE}} \left( 1 + \frac{R_5}{R_6 || R_7} \right) \]

and

\[ V_{\text{INL}} = \frac{R_5 || (R_7 + R_9)}{R_5} V_Z + V_{\text{BE}} \left( \frac{R_5 || (R_7 + R_9)}{R_5 || R_6 || (R_7 + R_9)} \right) \]

UVLO Hysteresis = \[ V_{\text{INH}} - V_{\text{INL}} = \left( \frac{R_5}{R_5 + R_7 + R_9} \right) V_Z + V_{\text{BE}} \left( \frac{R_5}{R_6 || R_7} - \frac{R_5 || (R_7 + R_9)}{R_6} \right) \]

The collector voltage of Q2 is made about 1.4V at the VIN lower trip voltage. This is necessary to prevent the UVLO circuit from interfering with the feedback amplifier in the LT1619.

Trickle Current Start from High Voltage Supplies

The low shutdown and idle mode quiescent supply currents of the LT1619 can be utilized to implement trickle current start from high voltage input sources (such as a 36V to 72V telecom bus). The trickle current start-up circuit in Figure 11 is modified from the UVLO circuit of Figure 10. R10 is a high value resistor that charges the storage capacitor C2 during start-up. Before \( V_{\text{CC}} \) reaches the upper UVLO trip point, Q2 holds the S/S pin low. The LT1619 draws shutdown mode current (\( \approx 15 \mu A \)) from \( V_{\text{CC}} \). Q2 collector can also be tied to the \( V_C \) pin through a diode as in Figure 10. The LT1619 will then draw idle mode quiescent current (\( \approx 140 \mu A \)) from \( V_{\text{CC}} \). R10 should be able to charge C2 while supplying current to the UVLO circuit and the LT1619. Maximizing R5 to R9 values reduces power dissipation in R10.

When \( V_{\text{CC}} \) crosses the upper UVLO threshold, the LT1619 starts switching and its current consumption increases. Before the bootstrap takes over, the LT1619 draws its current from C2. \( V_{\text{CC}} \) ramps towards the lower UVLO threshold. Increasing the value of C2 allows more time for the bootstrap circuit to establish itself before the converter enters undervoltage lockout.
Increasing Ramp Compensation While Synchronizing

The LT1619 is synchronized by forced discharge of the internal timing ramp. The timing ramp amplitude decreases as the synchronization frequency increases. Since the internal compensation ramp is derived from the timing ramp, reduced timing ramp results in diminished compensating ramp. If the LT1619 is synchronized at frequencies 20% to 30% higher than the free-running frequency, external ramp compensation will be required. Figures 12 and 13 show two such schemes.

In both figures the compensating ramps are kept linear by making R11-C1 and R14-C2 products substantially higher than the synchronizing period. The compensation ramps, whose peak amplitudes are made between 1/4 to 1/3 of the current limit threshold, are developed across R13. As a result, the effective current limit threshold is reduced by the sum of the compensating ramp and the offset voltage developed across R13 due to the SENSE pin input bias current (see Figure 5). Moreover, the current limit threshold becomes duty cycle dependent.

PC Board Layout and Other Practical Considerations

The following is recommended for PC board layout:

1. Trace lengths of the branches carrying switched current should be kept short. For example, in the boost converter of Figure 1, the circuit loop formed by M1, RSENSE, D1 and COUT carries switched current. The size of this loop must be minimized. RSENSE and COUT should be grounded to a single point on a large ground plane. This reduces switching noise and overall converter jitter. It is also preferable to ground the input capacitor C1 close to the common point between COUT and RSENSE although this is less important.

2. Keep the trace between the sense resistor and the SENSE pin short. When sensing high switch current, Kelvin connection to RSENSE is necessary.

3. Bypass both the VIN and DRV pins with ceramic capacitors next to the IC and the ground plane.

4. Keep high voltage switching nodes, such as the drain and gate of the MOSFET, away from the FB and VC pins.

5. Use inductor so that its ripple current is between 1/4 and 1/3 of its peak current. Steeper inductor current ramp results in sharper PWM comparator switching, hence less jitter.

6. In most cases, filtering the current sense signal is not necessary for jitter-free operation.

Figure 14 is the PC board layout for the 5V/8A and 12V/5A boost converters shown in Figures 15a and 16a.
Figure 14. Recommended Component Placement for the Boost Converters in Figures 15a and 16a
Figure 15a. 3.3V to 5V/8A Boost Converter

Figure 15b. Efficiency of the 5V/8A Boost Converter
Figure 16a. 5V to 12V/5A Boost Converter

Figure 16b. Efficiency of the 12V/5A Boost Converter
Figure 17a. 5V to –48V Cuk Converter

Figure 17b. Efficiency of the 5V to –48V Cuk
Figure 18a. Isolated Local SLIC Power Supply (Flyback) 20W Total Output Power (65V/0.3A or 32.5V/0.6A)

Figure 18b. Efficiency of the Isolated Local SLIC (Flyback)
PACKAGE DESCRIPTION

MS8 Package
8-Lead Plastic MSOP
(Reference LTC DWG # 05-08-1660)

NOTE:
1. DIMENSIONS IN MILLIMETER/INCH
2. DRAWING NOT TO SCALE
3. DIMENSION DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
   MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.152mm (.006") PER SIDE
4. DIMENSION DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSIONS.
   INTERLEAD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.152mm (.006") PER SIDE
5. LEAD COPLANARITY (BOTTOM OF LEADS AFTER FORMING) SHALL BE 0.102mm (.004") MAX
PACKAGE DESCRIPTION

S8 Package
8-Lead Plastic Small Outline (Narrow .150 Inch)
(Reference LTC DWG # 05-08-1610)

RECOMMENDED SOLDER PAD LAYOUT

NOTE:
1. DIMENSIONS IN INCHES (MILLIMETERS)
2. DRAWING NOT TO SCALE
3. THESE DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.
   MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED .006" (0.15mm)
**TYPICAL APPLICATION**

**Figure 19. 2.5W, 4VIN-28VIN to 5V/0.5A Nonisolated Supply**

**RELATED PARTS**

<table>
<thead>
<tr>
<th>PART NUMBER</th>
<th>DESCRIPTION</th>
<th>COMMENTS</th>
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</thead>
<tbody>
<tr>
<td>LT1370</td>
<td>500kHz, 6A Switching Regulator</td>
<td>Boost, Buck, Flyback, Forward, Inverting; 42V Switch Voltage</td>
</tr>
<tr>
<td>LT1372</td>
<td>500kHz, 1.5A Switching Regulator</td>
<td>SO-8, 2.7V ≤ VIN ≤ 30V, 42V Switch Voltage</td>
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<tr>
<td>LT1613</td>
<td>1.4MHz, SOT-23 DC/DC Converter</td>
<td>Fixed Frequency, 0.9V ≤ VIN ≤ 10V, 36V Switch Voltage</td>
</tr>
<tr>
<td>LTC1624</td>
<td>Switching Regulator Controller</td>
<td>SO-8, Drives N-Ch MOSFET, 3.5V ≤ VIN ≤ 36V</td>
</tr>
<tr>
<td>LT1680</td>
<td>Synchronous Boost Controller</td>
<td>Synchronous Operation for High Current/High Efficiency</td>
</tr>
<tr>
<td>LT1698</td>
<td>Isolated or Nonisolated 10W to 100W Power Supply Solution with Multiple Outputs</td>
<td>50% Lower Cost than Quarter Brick and Half Brick Modules Fits the Foot Print</td>
</tr>
<tr>
<td>LTC1871</td>
<td>No RSENSE Boost, Flyback, SEPIC Controller</td>
<td>2.5V ≤ VIN ≤ 36V, Current Mode Control, 50kHz to 1MHz Adjustable Frequency, MSOP-10</td>
</tr>
<tr>
<td>LTC1872</td>
<td>SOT-23 Boost Controller</td>
<td>550kHz Fixed Frequency, Current Mode</td>
</tr>
<tr>
<td>LT1946</td>
<td>1.2MHz, 65A DC/DC Converter</td>
<td>MSOP-8, 5V to 12V/400mA</td>
</tr>
<tr>
<td>LT3710/LT3781</td>
<td>Isolated or Nonisolated 10W to 100W Power Supply Solution with Multiple Outputs</td>
<td>50% Lower Cost than Quarter Brick and Half Brick Modules Fits the Foot Print</td>
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